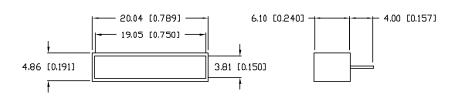
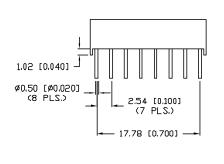


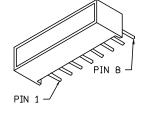
PART NUMBER SSB-LX2550GD REV.



ELECTRO-OPTICAL CH	ARACTER	ISTICS TA=25	5°C	If=20mA	
PARAMETER	MIN	TYP	MAX	LINITS	TEST COND
PEAK WAVELENCTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	$V_f$	
REVERSE VOLTAGE	5.0			٧r	I <sub>r</sub> = 1 00μΑ
AXIAL INTENSITY		40		mcd	$I_f = 20mA$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN	DIFFUSED			



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PARAMETER	MAX	UNITS	
PEAK FORWARD CURRENT*	150	mA	
STEADY CURRENT	25	mA	
POWER DISSIPATION	105	mW	
DERATE FROM 25°C	- 1.2	mW/°C	

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

 POWER DISSIPATION
 105
 mW

 DERATE FROM 25°C
 -1.2
 mW/°C

 OPERATING, STORAGE TEMP.
 -40 TO +85
 °C

 SOLDERING TEMP.
 + 260
 °C

 2.0mm FROM BODY
 3 SEC. MAX

\* t<10µS

\*\*UNLESS OTHERWISE SPECIFIED TOLERANGES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.006). LEAD SIZE=±0.05 (±0.002), LEAD S

REV. PART NUMBER
SSB-LX2550GD

5mm x 20mm 4 CHIP LIGHT BAR, 565nm GREEN CHIPS, GREEN DIFFUSED.

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CUR NAMY YEARS OF EXPERENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

LUMEX

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 SCALE:
 N/A